Notification Number:	otification Number: 20151012002 Notification Date: 12/01/201					2015			
Title: Datasheet update for HDC1000									
Customer Contact:	PCN Manager	Manager			Dept:		Quality Services		
Change Type:									
Assembly Site		Design				Wafer	Bump Site		
Assembly Process		Data Shee	t				Bump Materia	al	
Assembly Materials		Part number change		e			r Bump Process		
Mechanical Specification		Test Site				er Fab Site			
Packing/Shipping/Labeling Test Process		SS			Wafer	er Fab Materials			
						Wafer	r Fab Process		
Notification Details									
Description of Change:									
Texas Instruments Incorporated is announcing an information only notification.									
The product datasheet(s) is updated as seen in the change revision history below:									
			e enunge		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		-		
							TEXAS INSTRUMEN	TS	
HDC1000								10	
SNAS643B - JULY 2014 - REVISED SEPT	TEMBER 2015						www.ti.c	om	
Changes from Revision A (No	vember 2014) to Re	evision B					Pa	age	
Deleted references to operational and functional temperature range									
Added YPA package name							. 1		
Added Storage Temperature to Absolute Maximum Ratings table							5		
Changed Handling Ratings table title to ESD Ratings									
Changed temperature range									
Added RH to standard conditions							. 6		
Changed RH accuracy							. 6		
Added reference to Figure 2 for RH accuracy							6		
Added condition for hysteresis spec							. 6		
Changed the recommended operating range							6		
Changed Figure 2									
Changed : register reference for battery monitoring was corrected							10		
Added alternative recovery procedure for soldering									
Added Community Resources Section									
The detection with a supplement	will be changing	~							
The datasheet number v Device Family	viii be changing		nge From:				Change To:		
HDC1000		SNAS643A					SNAS643B		
IIDCI000		51750-55	n				SHASU45D		
Those changes may be	coviowed at the	datachoot	linke pro	vidod					
These changes may be reviewed at the datasheet links provided.									
http://www.ti.com/product/hdc1000									
Reason for Change: To more accurately reflect device characteristics.									
•				Dellak		(tive (persti		
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.									
Changes to product identification resulting from this Notification:									
None.									
Product Affected:									
HDC1000YPAR			HDC100	υτράι					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com